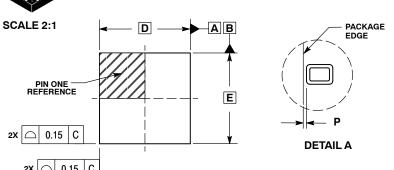
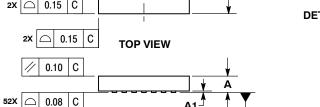
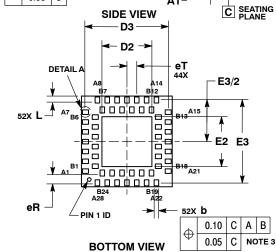


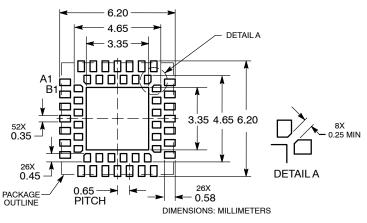
**DATE 29 MAR 2016** 







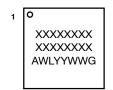
## **SOLDERING FOOTPRINT**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSIONS: MILLIMETERS. DIMENSION by APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.80	0.90	1.00	
A1	0.00	0.05	0.10	
b	0.15	0.20	0.25	
D	6.00 BSC			
D2	3.20	3.30	3.40	
D3	5.50 BSC			
E	6.00 BSC			
E2	3.20	3.30	3.40	
E3	5.50 BSC			
eT	0.65 BSC			
eR	0.65 BSC			
L	0.35	0.40	0.45	
Р	0.05 REF			

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code

= Assembly Location Α WL = Wafer Lot

YY = Year WW = Work Week

G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	QFN52 6x6, 0.65P		PAGE 1 OF 1	

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